

Sciosense Change Notification (CN)										
Originator:	Norber	t Breyer, Marketing		CN No:	CN-2020-005					
Product(s) affected:	TDC-GPX2 QFN64, 502050005									
Change date:	End Q2' 2021, samples available end Q1' 21									
		TYPE OF CHANGE								
🖂 Material 🗌 P	roduct	Process Equipment	nt 🗌	Specificat	ion 🗌 Other					
DESCR	IPTION	AND JUSTIFICATION OF (CHANG	E NOTE (C	N)					
- A new assembly line is selected to use standard lead frame material and therefore improve the standard lead time and reduce the risk of supply issues.										
Material to be change	d	Before Change		After Change						
phy. Dimension A (over all height)		Min Nom Max 0,80 0,85 0,90	Min Nom Max 0,80 0,85 0,90							
BOM										
Lead Frame Type:	Lead Frame Type:		C	Cu-AG EFTEC64T						
Ероху		8600		8200TI						
Bond Wire		0,8 mil AuPdCu G770HCD			mil AuPdCu					
Mold Compound	Mold Compound			G770HCD						
		SUPPORTING DATA								
Index area for Pin#1 I.D. marking		40mm (former 6.00mm)	-	-D2	Pin#1 I.D.					
т т т т т	Top view				ับบบบบบ <mark>ทุกบบบบบ</mark> ั					



	Package Dimension							
SYMBOL	Millimeter			Inches				
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
А	0.80	0.85	0.90	0.031	0.033	0.035		
A1	-	-	0.05	-	-	0.002		
A3		0.20 REF			0.008 REF			
b	0.20	0.25	0.30	0.008	0.010	0.012		
D	8.90	9.00	9.10	0.350	0.354	0.358		
D2	5.30	5.40	5.50	0.209	0.213	0.217		
E	8.90	9.00	9.10	0.350	0.354	0.358		
E2	5.30	5.40	5.50	0.209	0.213	0.217		
θ	0.50 BSC			0.020 BSC				
к	1.41 REF			0.056 REF				
L	0.30	0.40	0.50	0.012	0.016	0.020		

The marking will now come without ams Logo.



Ex. DEC. 2020 = 12/20

GPX2

Line 1: Fixed text Line 2: Assembly date code

CUSTOMER INFO & ACKNOWLEDGEMENT

Please acknowledge receipt of this CN by replying to <u>customersupport@sciosense.com</u> ScioSense is notifying you of this minor change and no further action is necessary from

you.

Please forward any queries regarding this CN to <u>customersupport@sciosense.com</u> keeping your account manager in copy.